

## Advanced Power MOSFET

SSP4N60AS

### FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25  $\mu$ A (Max.) @  $V_{DS} = 600V$
- Lower  $R_{DS(ON)}$  : 2.037  $\Omega$  (Typ.)

$BV_{DSS} = 600 V$

$R_{DS(on)} = 2.5 \Omega$

$I_D = 4 A$

TO-220



1.Gate 2. Drain 3. Source

### Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
$V_{DSS}$	Drain-to-Source Voltage	600	V
$I_D$	Continuous Drain Current ( $T_c=25^\circ C$ )	4	A
	Continuous Drain Current ( $T_c=100^\circ C$ )	2.5	
$I_{DM}$	Drain Current-Pulsed ①	16	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy ②	262	mJ
$I_{AR}$	Avalanche Current ①	4	A
$E_{AR}$	Repetitive Avalanche Energy ①	10	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	3.0	V/ns
$P_D$	Total Power Dissipation ( $T_c=25^\circ C$ )	100	W
	Linear Derating Factor	0.8	$\cdot \cdot ^\circ C$
$T_J , T_{STG}$	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

### Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{JC}$	Junction-to-Case	--	1.25	$^\circ C/W$
$R_{CS}$	Case-to-Sink	0.5	--	
$R_{JA}$	Junction-to-Ambient	--	62.5	

SAMSUNG

ELECTRONICS

# SSP4N60AS

N-CHANNEL  
POWER MOSFET

## Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	600	--	--	V	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.68	--	$\text{V}^\circ\text{C}$	$I_D=250\mu\text{A}$ See Fig 7
$V_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{\text{DS}}=5\text{V}, I_D=250\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage, Forward	--	--	100	nA	$V_{\text{GS}}=30\text{V}$
	Gate-Source Leakage, Reverse	--	--	-100	nA	$V_{\text{GS}}=-30\text{V}$
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	--	--	25	$\mu\text{A}$	$V_{\text{DS}}=600\text{V}$
		--	--	250		$V_{\text{DS}}=480\text{V}, T_C=125^\circ\text{C}$
$R_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	2.5	$\Omega$	$V_{\text{GS}}=10\text{V}, I_D=2\text{A}$ ④
$g_{\text{fs}}$	Forward Transconductance	--	3.32	--	$\text{S}$	$V_{\text{DS}}=50\text{V}, I_D=2\text{A}$ ④
$C_{\text{iss}}$	Input Capacitance	--	545	710	$\text{pF}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
$C_{\text{oss}}$	Output Capacitance	--	63	75		
$C_{\text{rss}}$	Reverse Transfer Capacitance	--	25	30		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	14	40	$\text{ns}$	$V_{\text{DD}}=300\text{V}, I_D=4\text{A}, R_G=12\Omega$ See Fig 13 ④ ⑤
$t_r$	Rise Time	--	16	45		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	49	110		
$t_f$	Fall Time	--	22	55		
$Q_g$	Total Gate Charge	--	25	34	$\text{nC}$	$V_{\text{DS}}=480\text{V}, V_{\text{GS}}=10\text{V}, I_D=4\text{A}$ See Fig 6 & Fig 12 ④ ⑤
$Q_{\text{gs}}$	Gate-Source Charge	--	4	--		
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge	--	11.9	--		

## Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$I_s$	Continuous Source Current	--	--	4	A	Integral reverse pn-diode in the MOSFET
$I_{\text{SM}}$	Pulsed-Source Current ①	--	--	16	A	
$V_{\text{SD}}$	Diode Forward Voltage ④	--	--	1.4	V	$T_J=25^\circ\text{C}, I_s=4\text{A}, V_{\text{GS}}=0\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time	--	350	--	ns	$T_J=25^\circ\text{C}, I_F=4\text{A}$
$Q_{\text{rr}}$	Reverse Recovery Charge	--	2.15	--	$\mu\text{C}$	$dI_F/dt=100\text{A}/\mu\text{s}$ ④

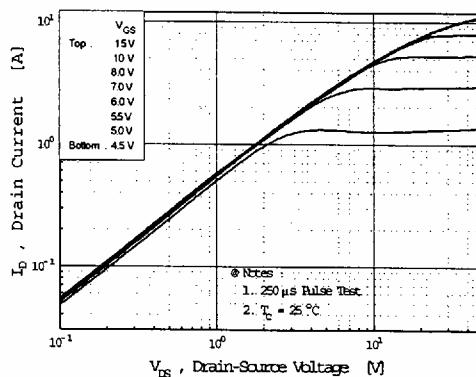
### Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ②  $L=30\text{mH}, I_{As}=4\text{A}, V_{Dc}=50\text{V}, R_G=2\Omega$ , Starting  $T_J=25^\circ\text{C}$
- ③  $I_{sd}\leq 4\text{A}, dI/dt\leq 100\text{A}/\mu\text{s}, V_{Dc}\leq BV_{DSS}$ , Starting  $T_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width =  $250\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

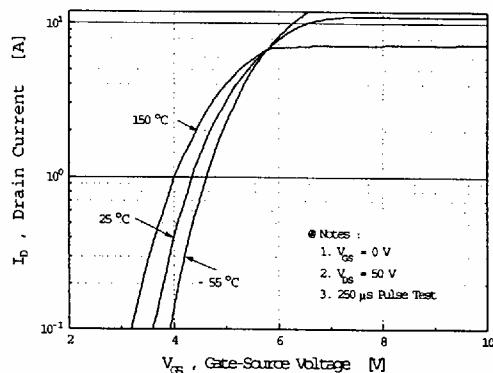
## N-CHANNEL POWER MOSFET

## SSP4N60AS

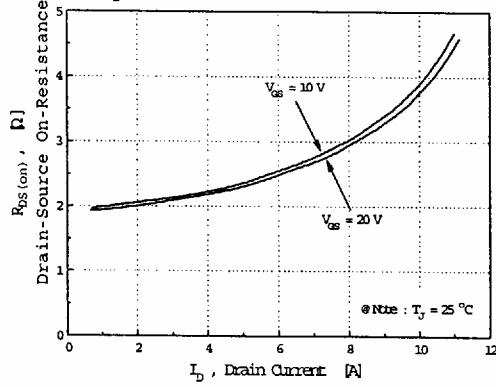
**Fig 1. Output Characteristics**



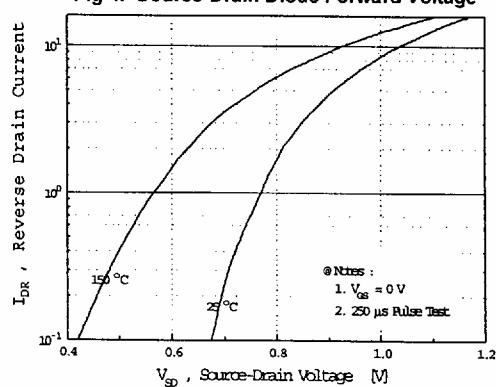
**Fig 2. Transfer Characteristics**



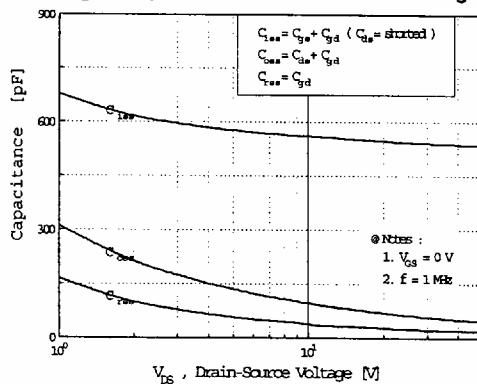
**Fig 3. On-Resistance vs. Drain Current**



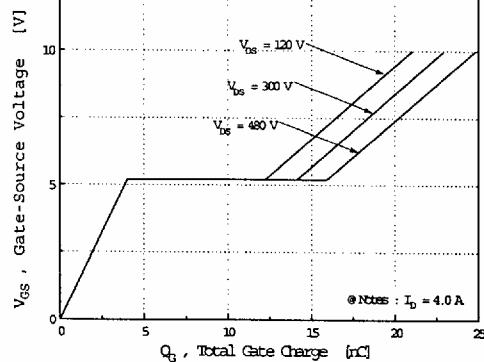
**Fig 4. Source-Drain Diode Forward Voltage**



**Fig 5. Capacitance vs. Drain-Source Voltage**

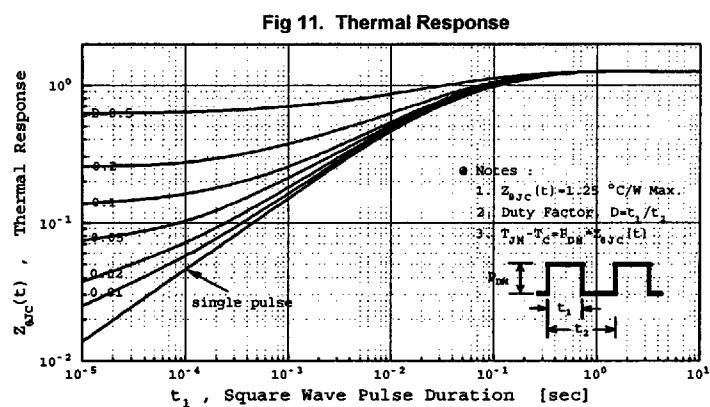
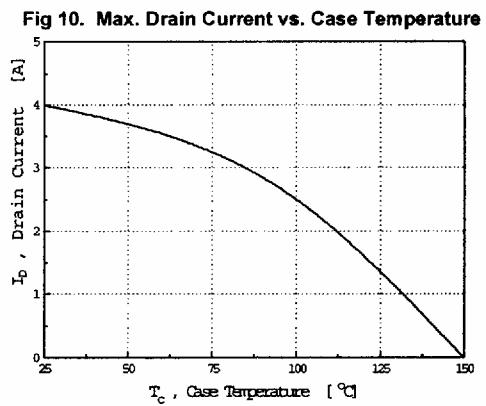
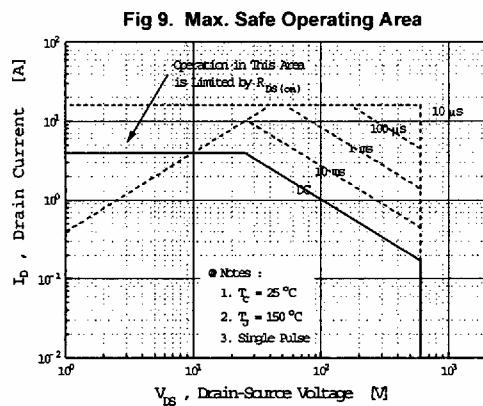
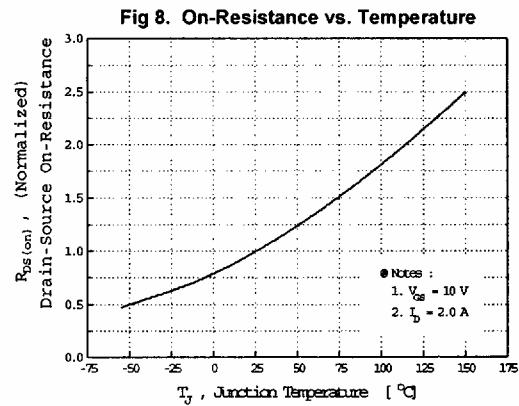
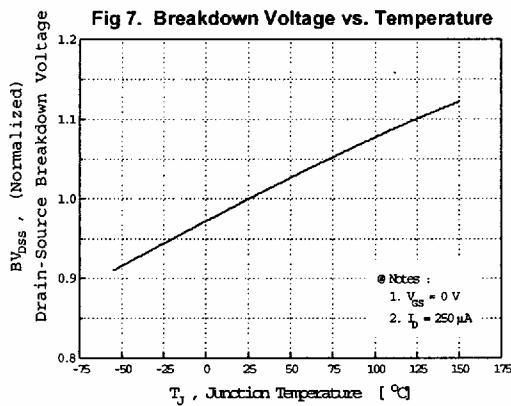


**Fig 6. Gate Charge vs. Gate-Source Voltage**



# SSP4N60AS

N-CHANNEL  
POWER MOSFET



N-CHANNEL  
POWER MOSFET

SSP4N60AS

Fig 12. Gate Charge Test Circuit & Waveform

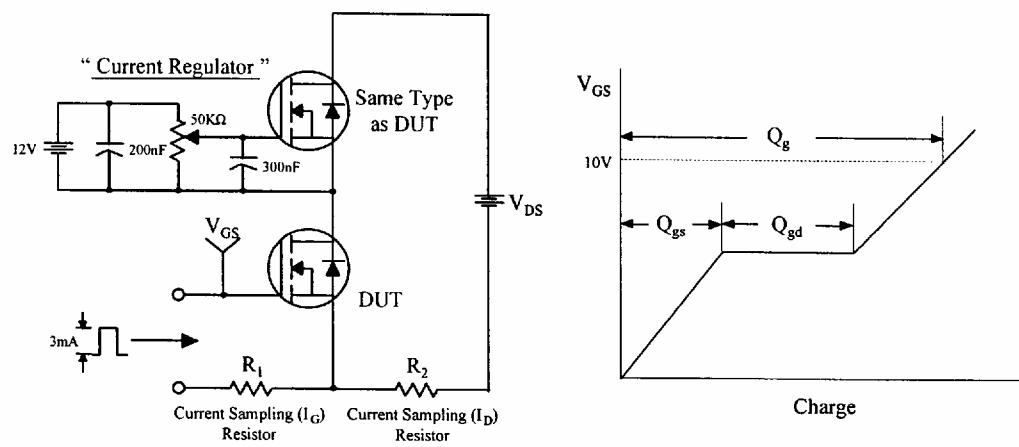


Fig 13. Resistive Switching Test Circuit & Waveforms

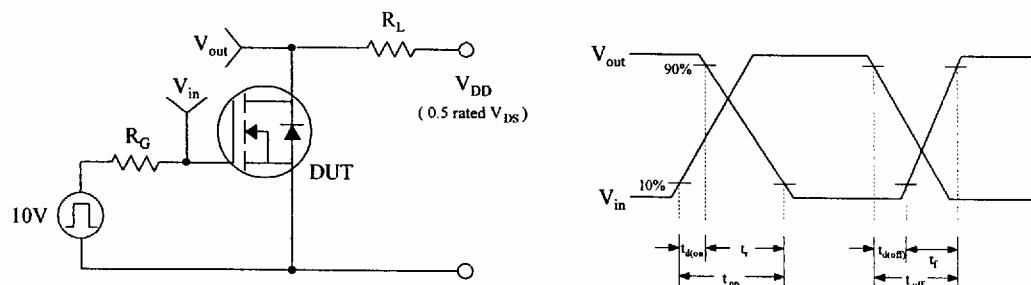
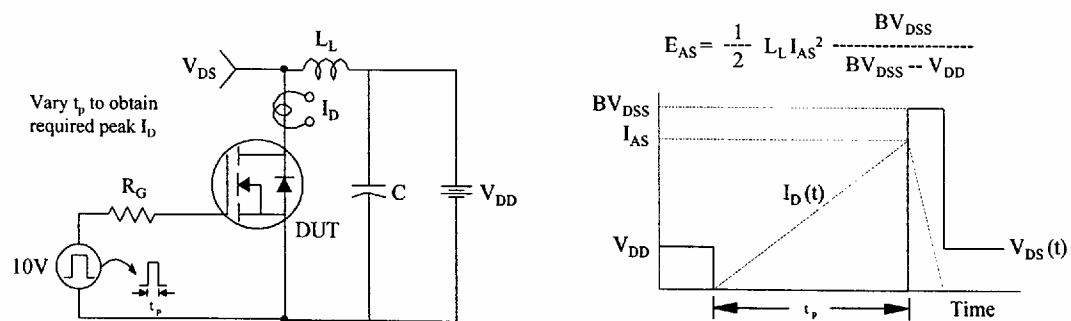


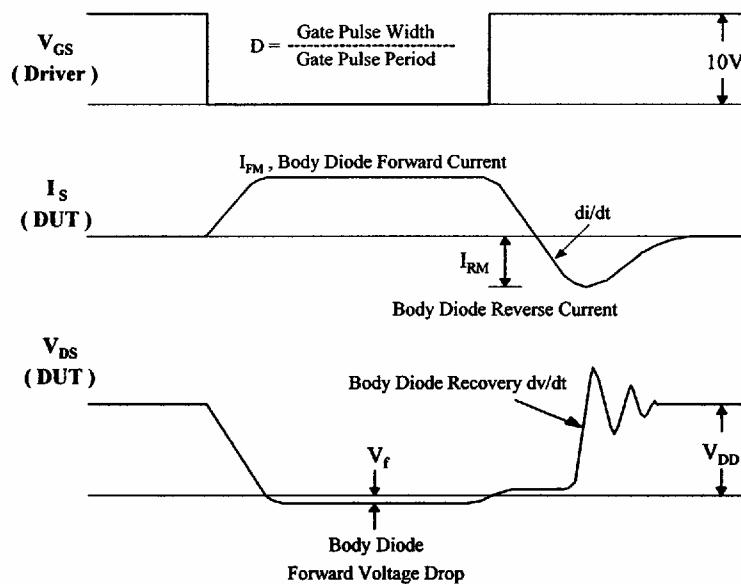
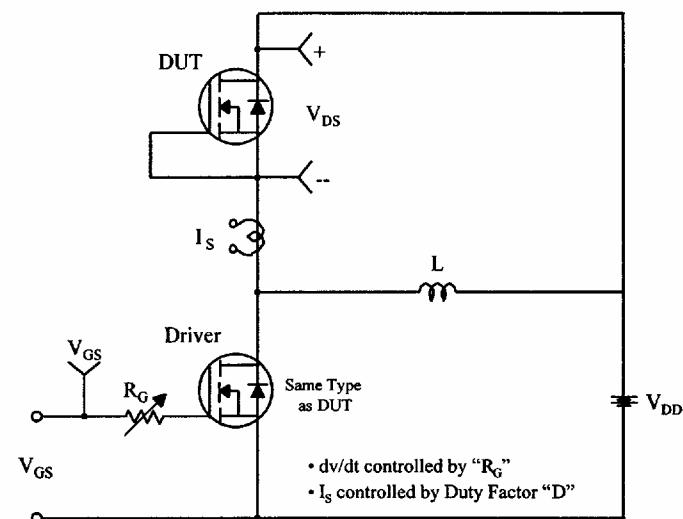
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



# SSP4N60AS

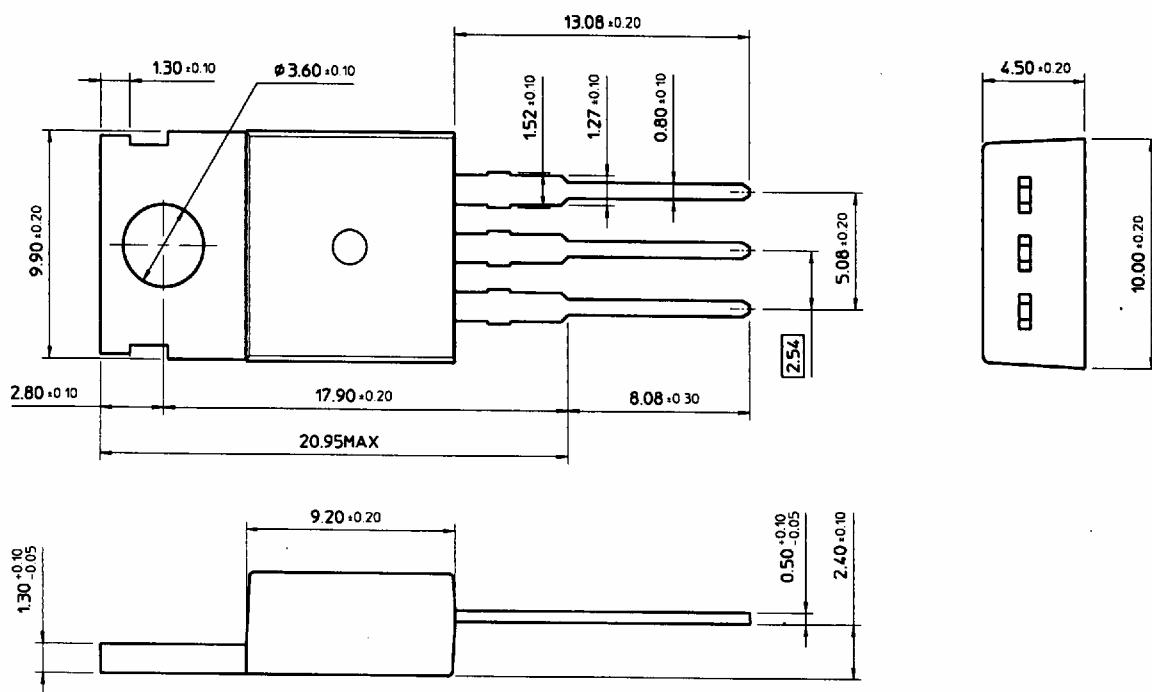
N-CHANNEL  
POWER MOSFET

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

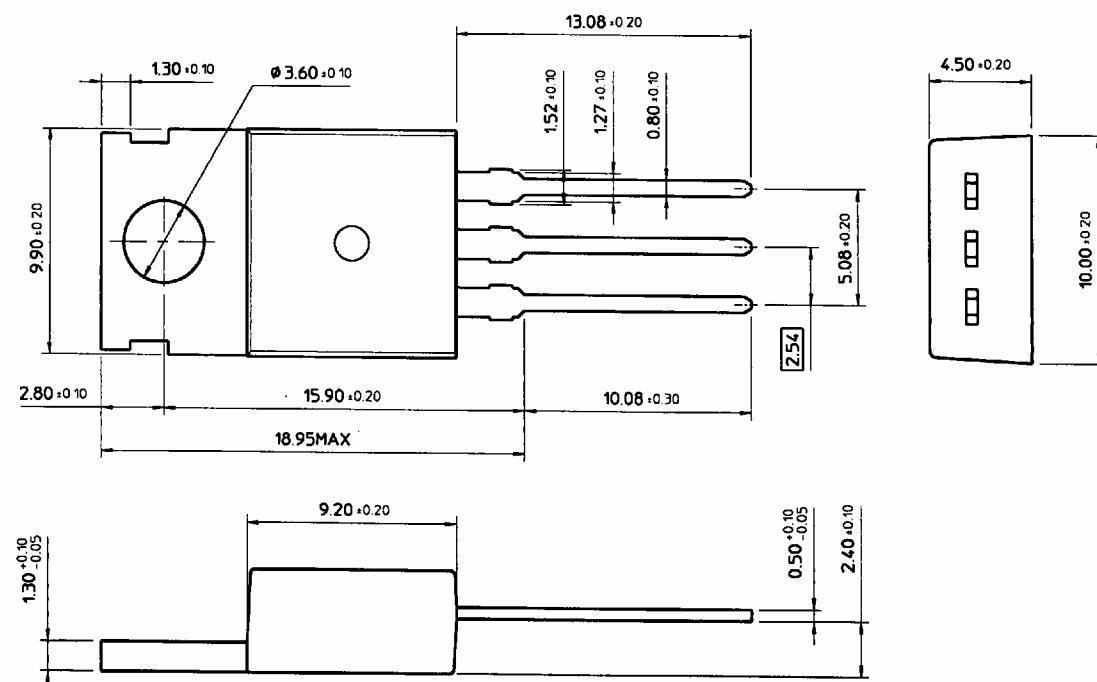


Dimensions in Millimeters

TO-220 (1)

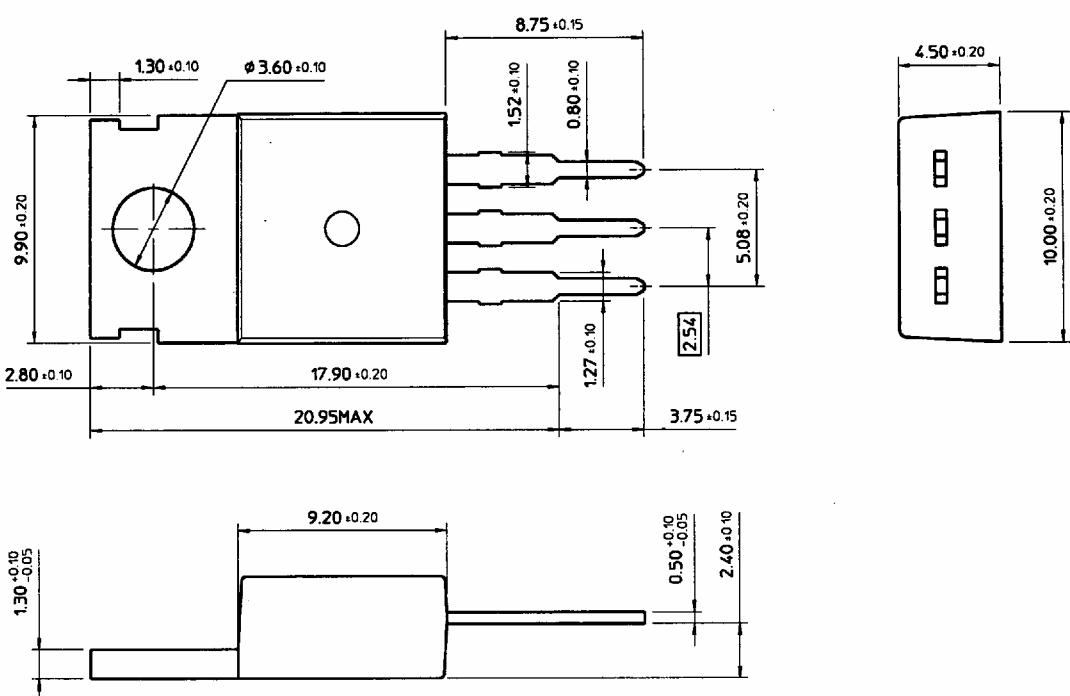


TO-220 (2)

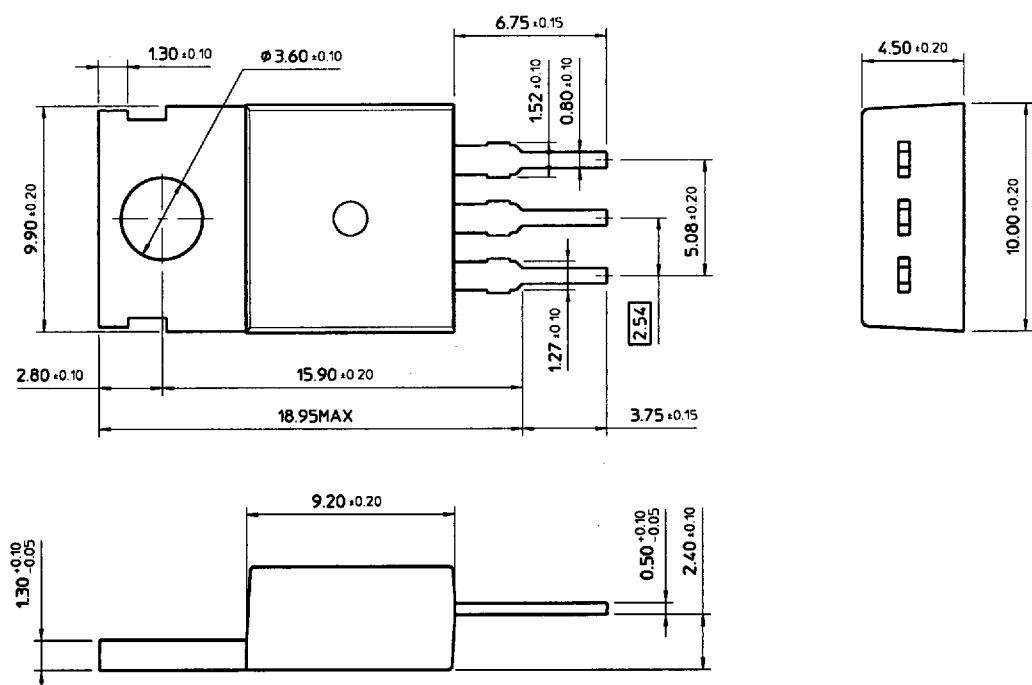


Dimensions in Millimeters

TO-220 (3)



TO-220 (4)



Dimensions in Millimeters

TO-220 (5)

